SHEET <u>1</u> OF <u>7</u>

INF	ORMATION CITATIO APPLIC	N IN AN	SURE	5920/FET/D		SERIAL NO. 09/943,383		
OIPE	(PTO-	1449)		APPLICANT SHANMUG	AM et al.			
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EXAMINER'S INITIALS	PATENT NO.	DATE		NAME	CLASS	SUBCLASS	FILING DATE	
A	4,796,194	01/03/89	Atherton				08/20/86	
	5,089,970	02/18/92	Lee et al.				10/05/89	
	5,108,570	04/28/92	Wang				03/30/90	
	5,220,517	06/15/93	Sierk et al.	Sierk et al.			08/31/90	
	5,236,868	08/17/93	Nulman				04/20/90	
	5,260,868	11/09/93	Gupta et al.				10/15/91	
	5,295,242	03/15/94	Mashruwala e	et al.			11/02/90	
	5,309,221	05/03/94	Fischer et al.				12/31/91	
	5,329,463	07/12/94	Sierk et al.				01/13/93	
	5,367,624	11/22/94	Cooper				06/11/93	
	5,398,336	03/14/95	Tantry et al.				06/16/93	
	5,402,367	03/28/95	Sullivan et al.				07/19/93	
	5,408,405	04/18/95	Mozumder et	al.			09/20/93	
	5,410,473	04/25/95	Kaneko et al.				12/16/92	
THE THE	,	FOI	REIGN PATEN	T DOCUMENTS		•		
EXAMINER'S INITIALS	PATENT NO.	DATE	(COUNTRY	CLASS	SUBCLASS	Translation Yes No	
6	01-283934	11/15/89	Japan				X	
50	2,050,247	08/29/91	Canada			<u> </u>	X	
				Γitle, Date, Pertine	ent Pages, Et	c.)	<u> </u>	
	Dishon, G., D. E	ylon, M. Fina	rov, and A. Shul	man. "Dielectric CN Nova Measuring Ir	MP Advanced		ol Based on	
	Runyan, W. R.,	and K. E. Bear	n. 1990. "Semico	onductor Integrated lishing Company.		ssing Technolo	ogy." pg. 48.	
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INF	ORMATION CITATIO APPLIC	SURE	ATTY. DOCKET N 5920/FET/DV	SERIAL NO. 09/943,383				
OIP	(PTO-	1449)		APPLICANT SHANMUGASUNDRAM et al.				
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EXAMINER'S INITIALS	PATENT NO.	DATE		NAME	CLASS	SUBCLASS	FILINC	DATE
	5,490,097	02/06/96	Swenson et al	•			08/06/	93
	5,495,417	02/27/96	Fuduka et al.	-			03/16/	93
	5,497,316	03/05/96	Sierk et al.				04/04/	95
	5,503,707	04/02/96	Maung et al.				09/22/	93
	5,508,947	04/16/96	Sierk et al.				05/13/	94
	5,629,216	629,216 05/13/97 Wijaranakula					02/27/	96
	5,657,254	08/12/97	Sierk et al.				04/15/	96
	5,661,669	08/26/97	Mozumder et	al.			06/07/	95
	5,694,325	12/02/97	Fukuda et al.				11/22/	95
	5,698,989	12/16/97	Nulman				09/13/	96
-	5,719,495	02/17/98	Moslehi				06/05/	96
	5,740,429	04/14/98	Wang et al.				07/07/	95
	5,751,582	05/12/98	Saxena et al.				09/24/	96
	5,754,297	05/19/98	Nulman	***			04/14/	97
	5,764,543	06/09/98	Kennedy				06/16/	95
	<u> </u>	FOI	REIGN PATEN	T DOCUMENTS	<u> </u>			
EXAMINER'S INITIALS	PATENT NO.	DATE		COUNTRY	CLASS	SUBCLASS	Trans	slation
							Yes	No
(A)	2,165,847	08/29/91	Canada				X	
0	2,194,855	08/29/91	Canada				X	
				itle, Date, Pertinent				
a	Zorich, Robert. California: Acad			egrated Circuit Manu	facturing.	pp. 464-498 S	an Dieg	0,
<u>a</u>	Rampalli, Prasae	d, Arakere Rar Managing Equ	nesh, and Nimish	i Shah. 1991. <i>CEPT—</i> ty and Availability in				
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æ	5,808,303	09/15/98	Schlagheck et a	1.			01/29/	97
	5,838,595	11/17/98	Sullivan et al.				11/25/	96
	5,883,437	03/16/99	Maruyama et al				12/28/	95
	5,910,011	06/08/99	Cruse	<u> </u>			05/12/	97
	6,054,379	04/25/00	Yau et al.				02/11/	98
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6	05-151231	06/18/93	Japan			 		X
	05-216896	08/27/93	Japan	<u> </u>	<u> </u>		<u> </u>	Х
	05-266029	10/15/93	Japan					X
	06-110894	04/22/94	Japan	,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,				X
	06-176994	06/24/94	Japan					X
	06-252236	09/09/94	Japan					X
	06-260380	09/16/94	Japan					X
	08-149583	06/07/96	Japan			· · · · · · · · · · · · · · · · · · ·	X	
-	09-34535	02/07/97	Japan				X	
	EP 0877308 A2	11/11/98	Europe			-	X	
 	11-67853	03/09/99	Japan				X	
(20)	1072967A3	11/21/01	Europe				X	
	OTH	<u> </u>	uding Author, T	itle, Date, Pertinent	t Pages, Et	c.)	1	
	Moyne, James R.,	Nauman Chau	dhry, and Roland	Telfeyan. 1995. "A	daptive Ex	tensions to a N	/lulti-Bra	anch
	Run-to-Run Contro	oller for Plasm	a Etching." Journ	al of Vacuum Science logy Manufacturing	e and Tech	anology. Ann A	Arbor,	
	Moyne, James, Ro	land Telfeyan,	Arnon Hurwitz, a	and John Taylor. Au	gust 1995.			
	Run-to-Run Contro	oller and Its Ap	oplication to Cher	nical-Mechanical Pla orkshop. Ann Arbor,	narization Michigan	." <i>SEMI/IEEE</i> The Universit	Advanc	ed higan
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EXAMINER'S INITIALS	PATENT APPLICATION NO.	FILING DATE	NAME		TITLE		CLASS	_	UB- _ASS
	09/363,966	07/29/99	Arackaparambil et al.		uter Integrated Manufacturing				
0	09/469,227	12/22/99	Somekh et al.	Multi-' Mediu	Tool Control System, Method	and			
6	09/619,044	07/19/00	Yuan	System	n and Method of Exporting or l Data in a Manufacturing Exec				
	09/637,620	08/11/00	Chi et al.	Generi	c Interface Builder				
•	09/656,031	09/06/00	Chi et al.	Manuf	ching Component for Associat facturing Facility Service Requ e Providers				
			FOREIGN P	ATENI	T DOCUMENTS	ž vijet m			
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2	Transform In: Transactions	frared Spec on Semicor	troscopy—Part II: iductor Manufactu	Real-Ti	"Epi-Film Thickness Measure ime in Situ Process Monitoring ol. 8, No. 3.	g and Contro	l." IEEE		
	Moyne, Arno	n Hurwitz, chanical Pl	and John Taylor. anarization Proces	October	ry, James Pugmire, Scott Shell 1995. "A Multi-Level Appro nneapolis, Minnesota: 42 nd Nat	ach to the Co	ontrol of	a	iam
6	Chang, E., B. Stine, T. Maung, R. Divecha, D. Boning, J. Chung, K. Chang, G. Ray, D. Bradbury, O. S. Nakagawa, S. Oh, and D. Bartelink. December 1995. "Using a Statistical Metrology Framework to Identify Systematic and Random Sources of Die- and Wafer-level ILD Thickness Variation in CMP Processes." Washington, D.C.: International Electron Devices Meeting.								
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60			andard for Defini SEMI E10-96.	tion and l	Measurement of Equipment Re	eliability, Av	allability,	, and	
	Shellman, and Trans. CPMT	i John Tayl (<i>C)</i> , Vol. 1	or. October 1996 9, No. 4, pp. 307	6. "Run l 7-314.	nes Moyne, Roland Telfeyan, Aby Run Control of Chemical-M	lechanical P	olishing."		
	CMP Pad We Conference.	ar Using R	un by Run Feedb	ack Cont	n Hurwitz, and John Curry. Ju rol." Santa Clara, California:	VLSI Multil	evel Inter		
6	February 199 Speciality Co	6. "On-Linnferences,	e Integrated Met 1 st International C	rology fo CMP Plan	Schraub, D. Trojan, 4 th Stamb or CMP Processing." Santa Cla narization Conference.	ara, Californ	ia: VMIC		
					itle, Date, Pertinent Pages, E				
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EXAMINER'S INITIALS	PATENT NO.	DATE	COUNTRY		CLASS		SUB- CLASS	Tran Yes	islation No
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(d)	09/928,473	08/14/01	Koh	Tool Se	rvices Layer for Providing Toons in Conjunction with Tool Fu	ol Service			
	09/927,444	08/13/01	Ward et al.		c Control of Wafer Processing				
	09/811,667	03/20/01	Yuan et al.		olerant and Automated Compute Workflow	ter			
	09/800,980	03/08/01	Hawkins et al.	Dynami	c and Extensible Task Guide	_			
	09/725,908	11/30/00	Chi et al.	Dynami	c Subject Information Generate e Services of Distributed Object				
	09/655,542	09/06/00	Yuan	Palettes	Method and Medium for Defi to Transform an Application I e for a Service				
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SHEET <u>6</u> OF <u>7</u>

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0			icrochip Fabricati New York: McGr		Practical Guide to Semicondu	ictor Proces.	sing. Thir	d Edi	tion,
	Campbell, W.	Jarrett, and	Anthony J. Topra ed Micro Devises,	c. Feb	ruary 11-12, 1998. "Run-to-	Run Control	in Micro	electro	onics
	Edgar, Thomas	s F., Stepha	nie W. Butler, Jar	rett Car	mpbell, Carlos Pfeiffer, Chris	Bode, Sung	Bo Hwa	ng, an	ıd
1					ol in Microelectronics Manufa	acturing: Pra	ctices, Cl	nallen	ges,
	Movne James	es." Autom	natica, Vol. 36, pp.	. 136/- "A Fi	1603, 2000. Illy Automated Chemical-Me	chanical Plan	narization	Proc	ess."
					ection (V-MIC) Conference.				
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	Mountain Viev	w, Californi	a: SEMI Standard	s. SEN	/II Draft Doc. 2817.	Linkty O			
	Consilium. Au View, Californ			ent Col	mponent: QMC™ and QMC-	Link''' Over	view. M	ountai	111
1				llah Kh	nan, Rock Nadeau, Paul Smith	n, John Colt,	Jonathan	Chap	ple-
	Sokol, and Tai	un Parikh.	November 1998.	"Multi	zone Uniformity Control of a	CMP Proce			
					gton: SEMETECH Symposiu	m.		-	
					ifornia: Consilium, Inc.	1000 "	D 4		Au 1
6			or Solakhain, Anth s." Ann Arbor, M		cci, Tier Gu, and James Moy n.	ne. 1998. "I	Kun-to-R	un Co	ntrol
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	paper and pres Manufacturing	entation to) : 196 th Meet	Third International ting of the Electroc	l Syn	CMP Process Automation a posium on Chemical Mecha ical Society.				
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	Koliopoulus, D Effects on CM Research Socie	Dale Hetheri P: Experime ety Spring M	ngton, HongJiang Sental Validation of Secting.	Sun, Mod	Noel Poduje, Pat Hester, Yor and Michael Lacy. April 20 eling Methods." San Franci	01. "Wafer N sco, Californi	lanotopog a: Materia	graphy als	<i>'</i>
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INF	ORMATION CITATIO APPLIC	N IN AN	SURE	ATTY. DOCKE 5920/FET/DV	SERIAL NO. 09/943,383 SEP 20 2002 SEP 20 2002 SERIAL NO. 09/943,383			
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EXAMINER'S INITIALS	PATENT NO.	DATE		NAME	CLASS	SUBCLASS		G DATE
	4,698,766	10/06/87	Entwistle et al.			`	05/17	
	4,967,381	10/30/90	Lane et al.		,	1	07/06	
	5,208,765	05/04/93	Turnbull		1.	1	07/20	/90
	5,226,118	07/06/93	Baker et al.		111		01/29	
	5,231,585	07/27/93	Kobayashi et a	d.	1.11	1	06/20	/90
	5,420,796	05/30/95	Weling et al.		,		12/23	/93
	5,469,361	11/21/95	Moyne		``		06/06	/94
	5,525,808	06/11/96	Irie et al.		in (12/20	/94	
	5,586,039	12/17/96	17/96 Hirsch et al.				02/27	795
	5,603,707	02/18/97	Trombetta et a	1.			11/28	/95
	5,664,987	09/09/97	Renteln				09/04	/96
	5,812,407	09/22/98	Sato et al.				08/12	./97
	5,828,778	10/27/98	Hagi et al.				06/12	./96
	5,832,224	11/03/98	Fehskens et al.				06/14	/96
		FOI	REIGN PATENT	Γ DOCUMENTS				
EXAMINER'S INITIALS	PATENT NO.	DATE	C	OUNTRY	CLASS	SUBCLASS	Tran	slation
INITIALS							Yes	No
	61-171147	08/01/86	Japan					Х
	6-184434	07/05/94	Japan					X
	0 621 522 A2	10/26/94	Europe				Х	
	8-50161	02/20/96	Japan					Х
	8-304023	11/22/96	Japan					X
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	Step and Repeat	Lithographic	Cameras." IBM	itu Measurement a Technical Disclosubility of a Step and	ire Bulletin, p	p. 4855-4859.		
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EXAMINER'S INITIALS	PATENT NO.	DATE	<u> </u>	NAME	CLASS	SUBCLASS	FILING	DATE	
INITIALS	5,859,964	01/12/99	Wang et al.	IVAIVIE	CLASS	SUBCLASS	10/25/	96	
	5,863,807	01/26/99	Jang et al.				03/15/		
	5,870,306	02/09/99	Harada				06/13/		
	5,903,455	05/11/99	Sharpe, Jr. et a	 1.			12/12/		
	5,916,016	06/29/99	Bothra				10/23/		
	5,923,553	07/13/99	Yi				10/05/	96	
	5,930,138	07/27/99	Lin et al.			-	09/10/	97	
	5,940,300	08/17/99	Ozaki				05/08/	97	
	5,960,214	09/28/99	Sharpe, Jr. et a	1.			12/04/	96	
	5,963,881	10/05/99	Kahn et al.	-			10/20/	97	
	5,982,920	11/09/99	Tobin, Jr. et al.				01/08/	97	
	6,041,270	03/21/00	Steffan et al.				12/05/	97	
	6,078,845	06/20/00	Friedman				11/25/	96	
	6,112,130	08/29/00	Fukuda et al.				10/01/	97	
	6,148,246	11/14/00	Kawazome				06/10/	98	
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HALLINGS							Yes	No	
	0 747 795 A2	12/11/96	Europe				Х		
	10-173029	06/26/98	Japan					X	
	0 895 145 A1	02/03/99	Europe				X		
	11-126816	05/11/99	Japan					X	
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EXAMINER'S INITIALS	PATENT NO.	DATE		NAME	CLASS	SUBCLASS	FILING	G DATE
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	6,178,390	01/23/01	Jun				09/08/	98
	6,185,324	02/06/01	Ishihara et al.				01/31/	95
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	11-135601	05/21/99	Japan		<u> </u>			$\frac{1}{x}$
	WO 00/05759	02/03/00	WO		<u> </u>		X	
	WO 00/35063	06/15/00	wo			<u> </u>	X	
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